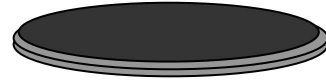
Shin-Etsu

SFX524A

Application

Wafer scale spin-coatable B-stage die attach material



Features

・Good spin-coatability
・Good flatness after spin-coat
・Short time B-stageable(120C/10min)
・After B-staged material is stable (6months@25C)
・Good release performance from dicing film (standard and UV type).

Properties

Paste properties	Test method	SFX524A
Viscosity	CP42/10rpm	3Pa・s
Pot life	in syringe	168hr
Shelf life	-40℃	1year

Spin-coat condition	
500rpm/30sec + 1000rpm/30sec	After B-stage thickness 45 μm
500rpm/30sec + 2000rpm/30sec	After B-stage thickness 25 μm
500rpm/30sec + 4000rpm/30sec	After B-stage thickness 15 μm

B-stage properties		
B-stage condition		120℃/10min
Pot life of after B-stage		6months/25C
Die attaching condition	Die temperature	25～150℃
	Substrate temperature	150℃
	Pressure	0.5MPa
	Time	0.5sec

Post cure properties	Test method	SFX524A
Cure condition	RT～125℃/30min + 125℃/1hr + 125℃～165℃/30min + 165℃/2hr	
Tensile modulus	DMA25℃ 0.2mmt	1500MPa
	DMA125℃ 0.2mmt	500MPa
Glass transition temp.	TMA	120℃
Coefficient of thermal expansion	TMA -50℃～0℃	68ppm
	TMA 180℃～230℃	153ppm
Die share strength	2.5mm□Si to Si Post cure	27MPa
	2.5mm□Si to Si MSL1＋IR260℃	23MPa

How to Use SFX524A

Shin-Etsu